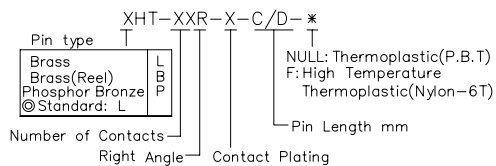
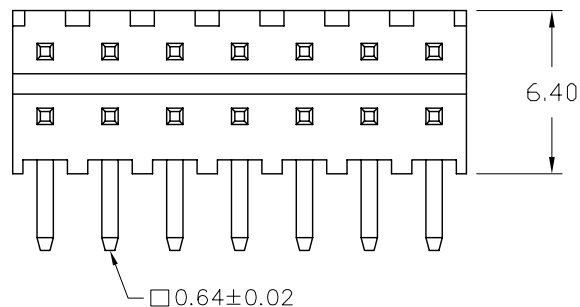


No. of Contacts	DIMENSIONS		REMARK (備註)
	A	B	
4	2.54	5.08	○
6	5.08	7.62	○
8	7.62	10.16	○
10	10.16	12.70	○
12	12.70	15.24	○
14	15.24	17.78	○
16	17.78	20.32	○
18	20.32	22.86	○
20	22.86	25.40	○
22	25.40	27.94	○
24	27.94	30.48	○
26	30.48	33.02	○
28	33.02	35.56	○
30	35.56	38.10	○
32	38.10	40.64	○
34	40.64	43.18	○
36	43.18	45.72	○
38	45.72	48.26	○
40	48.26	50.80	○
42	50.80	53.34	○
44	53.34	55.88	○
46	55.88	58.42	○
48	58.42	60.96	○
50	60.96	63.50	○
52	63.50	66.04	○
54	66.04	68.58	○
56	68.58	71.12	○
58	71.12	73.66	○
60	73.66	76.20	○



Definition	Code
◎ Tin plated	A
◎ Gold plated:	
15μ 0.02 μm (Au)	B 15μ* 0.75 μm (Au)
10μ 0.02 μm (Au)	E 30μ* 0.75 μm (Au)
◎ Duplex plating:	
15μ 0.02 μm (Au)	K 15μ* 0.75 μm (Au)
10μ 0.02 μm (Au)	N 30μ* 0.75 μm (Au)
◎ Standard:	B
◎ Prefix 'V' means lead free plating	

SPECIFICATIONS

Current Rating: 3 Amps
 Insulator resistance: 5000 Megohms min.
 Dielectric withstanding: AC 1000 V
 Operating Temperature: -40°~+105°C
 Contact Material: Copper alloy
 Insulator Material: Thermoplastic, UL 94V-0 (PBT)
 Color: Black

Finish: Tin, Gold plated
 ◎ Standard: Gold flash all over

◎ For illustration purpose the XHT-XXR-X-035/030 was shown
 Recommended PCB Layout (PCB TOLERANCE ±0.05)

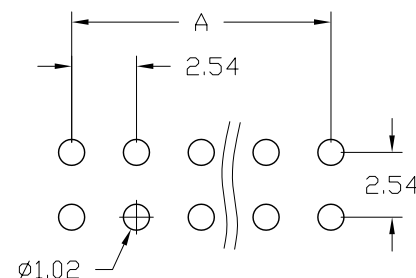
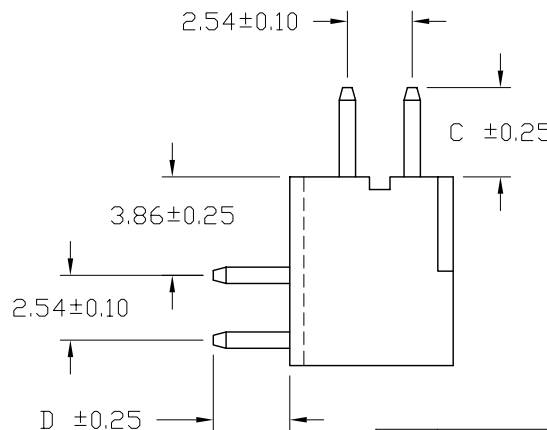
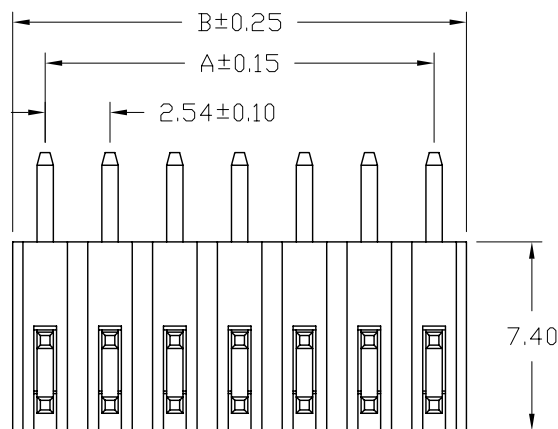


Diagram	Molding description
○	mass production & assemble mold
◎	sample & assemble mold
⊕	mass production & fix mold
⊕	sample & fix mold



Rev.	ECN Number	Description	Drawn	Date
3	ECR-4B0102	修改電鍍說明	陳顯鑫	11/25 04'
4	EC2-520178	新增\NYLON-6T材質選項	陳顯鑫	02/14 05'
5	EC2-580038	新增XHT-XXR-X-100/030	陳顯鑫	08/09 05'



GENERAL TOLERANCE	SCALE 1=1	ORIGINAL DRAWN 洪銀雯	DATE 07/27/04'	DWG. NO. 3-25	TITLE 2.54X2.54mm HEADER (成品規格圖)	REV. 5
XX. ± 0.50	UNIT MM	CHECK 林錫錦	DATE 08/09 05'	F: \DWG\CDWG\HT\HTR1U.DWG	SHEET 1/2	
X. ± 0.30	SIZE A4/2	APPROVE 林錫錦	DATE 08/09 05'	PARTS NO. XHT-XXR-X-C/D-*		
.X ± 0.25						
.XX ± 0.20						